

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











74LVC1G06

#### SINGLE INVERTER BUFFER/DRIVER WITH OPEN DRAIN OUTPUT

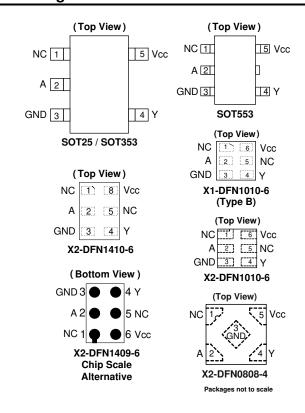
#### **Description**

The 74LVC1G06 is a single inverter gate with an open drain output. The device is designed for operation with a power supply range of 1.65V to 5.5V. The input is tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output preventing damaging current backflow when the device is powered down. The open-drain output can be connected to other open drain outputs to implement active-low wired-OR or active-high wired-AND functions. The maximum sink current is 32mA.

#### **Features**

- Wide Supply Voltage Range from 1.65 to 5.5V
- 24mA Sink Current at 3.3V
- CMOS Low Power Consumption
- I<sub>OFF</sub> Supports Partial-Power-Down Mode Operation
- Inputs Accept up to 5.5V
- ESD Protection Tested per JESD 22
  - Exceeds 200-V Machine Model (A115)
  - Exceeds 2000-V Human Body Model (A114)
  - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Range of Package Options
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

#### **Pin Assignments**



#### **Applications**

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products Such as:
  - PCs, Networking, Notebooks, Netbooks, PDAs
  - Tablet Computers, E-readers
  - Computer Peripherals, Hard Drives, CD/DVD ROM
  - TV, DVD, DVR, Set Top Box
  - Cell Phones, Personal Navigation / GPS
  - MP3 Players ,Cameras, Video Recorders

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



#### Ordering Information (Note 4)

74 LVC1G 06 XXX -7 **Logic Device Function Package Packing** 

74 : Logic Prefix LVC: 1.65 to 5.5 V **Logic Family** 1G: One Gate

06: 1-Input **Inverter Buffer** with open drain output

W5: SOT25 **SE: SOT353** Z:SOT553

-7: 7" Tape & Reel

FS3: X2-DFN0808-4 FW5: X1-DFN1010-6 (Type B)

FW4:X2-DFN1010-6 FX4: X2- DFN1409-6 FZ4: X2- DFN1410-6

Dout Number	Dookses Code	Package	Package	7" Tape and Reel		
Part Number	Package Code	(Notes 5 & 6)	Size	Quantity	Part Number Suffix	
74LVC1G06W5-7	W5	SOT25	3.0mm x 2.8mm x 1.2mm 0.95 mm lead pitch	3,000/Tape & Reel	-7	
74LVC1G06SE-7	SE	SOT353	2.0mm x 2.0mm x 1.1mm 0.65 mm lead pitch	3,000/Tape & Reel	-7	
74LVC1G06Z-7	Z	SOT553	1.6mm x 1.6 mm x 0.62mm 0.5 mm lead pitch	4,000/Tape & Reel	-7	
74LVC1G06FS3-7	FS3	X2-DFN0808-4	0.8mm x 0.8 mm x 0.35mm 0.5 mm pad pitch (diamond)	5,000/Tape & Reel	-7	
74LVC1G06FW5-7	FW5	X1-DFN1010-6 (Type B)	1.0mm x 1.0mm x 0.5mm 0.35 mm pad pitch	5,000/Tape & Reel	-7	
74LVC1G06FW4-7	FW4	X2-DFN1010-6	1.0mm x 1.0mm x 0.4mm 0.35 mm pad pitch	5,000/Tape & Reel	-7	
74LVC1G06FX4-7	FX4	X2-DFN1409-6 Chip scale alternative	1.4mm x 0.9mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7	
74LVC1G06FZ4-7	FZ4	X2-DFN1410-6	1.4mm x 1.0mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel -7		

Notes:

- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.
- 5. Pad layout as shown on Diodes Inc. suggested pad layout which can be found on our website at http://www.diodes.com/package-outlines.html.
  6. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.

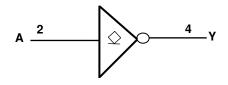
### **Pin Descriptions**

Pin Name	Description
NC	No Connection
Α	Data Input
GND	Ground
Υ	Data Output
V <sub>CC</sub>	Supply Voltage

# **Function Table**

Inputs	Output
Α	Υ
Н	L
L	Z

### **Logic Diagram**





# Absolute Maximum Ratings (Notes 7 & 8) (@TA = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V <sub>CC</sub>	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage Applied to Output in High Impedance or IOFF State	-0.5 to 6.5	V
Vo	Voltage Applied to Output in High or Low State.	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	Input Clamp Current V <sub>I</sub> < 0	-50	mA
I <sub>OK</sub>	Output Clamp Current	-50	mA
I <sub>O</sub>	Continuous Output Current	±50	mA
I <sub>CC</sub> , I <sub>GN</sub>	Continuous Current Through V <sub>CC</sub> or GND	±100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C

Notes:

# Recommended Operating Conditions (Note 9) (@TA = +25°C, unless otherwise specified.)

Symbol		Parameter	Min	Max	Unit	
Vcc	Operating Voltage	Operating	1.65	5.5	V	
A CC	Operating Voltage	Data retention only	1.5	_	V	
		$V_{CC} = 1.65V$ to 1.95V	0.65 x V <sub>CC</sub>	_		
M	High Lovel Input Voltage	$V_{CC} = 2.3V$ to 2.7V	1.7	_	V	
$V_{IH}$	High-Level Input Voltage	$V_{CC} = 3V$ to 3.6V	2	_	V	
		V <sub>CC</sub> = 4.5V to 5.5V	0.7 x V <sub>CC</sub>	_		
		V <sub>CC</sub> = 1.65V to 1.95V	_	0.35 x V <sub>CC</sub>		
V	Low-Level Input Voltage	V <sub>CC</sub> = 2.3V to 2.7V	_	0.7	M	
$V_{IL}$		V <sub>CC</sub> = 3V to 3.6V	_	0.8	V	
		V <sub>CC</sub> = 4.5V to 5.5V	_	0.3 x V <sub>CC</sub>		
Vı	Input Voltage		0	5.5	V	
Vo	Output Voltage		0	5.5	V	
		V <sub>CC</sub> = 1.65V	_	4		
		$V_{CC} = 2.3V$	_	8		
la.	Low-Level Output Current	$V_{CC} = 2.7V$	_	12	mA	
l <sub>OL</sub>	Low-Level Output Outrent	V <sub>CC</sub> = 3V	_	16	IIIA	
		ACC = 2A	_	24		
		$V_{CC} = 4.5V$	_	32		
		$V_{CC} = 1.8V \pm 0.15V, 2.5V \pm 0.2V$	_	20		
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 3.3V \pm 0.3V$	<u> </u>		ns/V	
		$V_{CC} = 5V \pm 0.5V$		5		
TA	Operating Free-Air Temperature	_	-40	+125	°C	

Note: 9. Unused inputs should be held at V<sub>CC</sub> or Ground.

<sup>7.</sup> Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device

operation should be within recommend values.

8. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.



# Electrical Characteristics (All typical values are at V<sub>CC</sub> = 3.3V, T<sub>A</sub> = +25°C)

Cumphal	Davamatav	Took Conditions	V	-4	10°C to +85°	Č	-40°C to	+125°C	l lesia
Symbol	Parameter	Test Conditions	V <sub>CC</sub>	Min	Тур	Max	Min	Max	Unit
		I <sub>OL</sub> = 100μA	1.65V to 5.5V	_	_	0.1	_	0.1	
		I <sub>OL</sub> = 4mA	1.65V	_	_	0.45	_	0.7	
		I <sub>OL</sub> = 8mA	2.3V	_	_	0.3	_	0.45	
$V_{OL}$	Low Level Output Voltage	I <sub>OL</sub> = 12mA	2.7	_	_	0.4	_	0.6	V
	Catput Voltage	I <sub>OL</sub> = 16mA	01/	_	_	0.4	_	0.6	
		I <sub>OL</sub> = 24mA	3V	_	_	0.55	_	0.8	
		I <sub>OL</sub> = 32mA	4.5V	_	_	0.55	_	0.8	
II	Input Current	V <sub>I</sub> = 5.5 V or GND	0 to 5.5V	_	± 0.1	±5	_	± 100	μΑ
l <sub>OFF</sub>	Power Down Leakage Current	V <sub>I</sub> or V <sub>O</sub> = 5.5V	0V	_	_	±10	_	±200	μA
Icc	Supply Current	V <sub>I</sub> = 5.5V or GND I <sub>O</sub> = 0	5.5V	_	0.1	10	_	200	μA
Δlcc	Additional Supply Current	Input at V <sub>CC</sub> - 0.6 V	3V to 5.5V	_	_	500	_	5,000	μA
Ci	Input Capacitance	$V_i = V_{CC} - or GND$	3.3V	_	5	_	_	_	pF



# Package Characteristics (All typical values are at $V_{CC} = 3.3V$ , $T_A = +25$ °C)

Symbol	Parameter	Test Conditions	Vcc	Min	Тур.	Max	Unit
		SOT25		_	204	_	
		SOT353		_	371	_	
		SOT553		_	231	_	
	Thermal Resistance	X2-DFN0808-4	(Note 10)	_	400	_	°C/W
$\theta_{JA}$	Junction-to-Ambient	X1-DFN1010-6 (Type B)	(Note 10)	_	435	_	- C/VV
		X2-DFN1010-6		_	445	_	
		X2-DFN1409-6		_	470	_	
		X2-DFN1410-6		_	460	_	
		SOT25		_	52	_	
		SOT353		_	143	_	
		SOT553		_	105	_	
	Thermal Resistance	X2-DFN0808-4	(Note 10)	_	225	_	0CAM
A1C	θ <sub>JC</sub> Junction-to-Case	X1-DFN1010-6 (Type B)	(Note 10)	_	250	_	°C/W
		X2-DFN1010-6		_	250	_	
		X2-DFN1409-6			275		
		X2-DFN1410-6		_	265	_	

Note: 10. Test condition for each of the 8 package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

# **Switching Characteristics**

Figure 1 Typical Values at  $T_A = +25^{\circ}C$  and nominal voltages 1.8V, 2.5V, 2.7V, 3.3V, and 5.0V.

Parameter	From	То	V	TA	= -40°C to +8	5°C	T <sub>A</sub> = -40°C	to +125°C	Unit
Parameter	Input	Output	V <sub>CC</sub>	Min	Тур	Max	Min	Max	Oilit
			1.8V ± 0.15V	1.0	3.0	6.5	1.0	8.5	
			2.5V ± 0.2V	0.5	1.9	4.0	0.5	5.5	
t <sub>pd</sub>	A or B	Υ	2.7V	0.5	2.5	4.5	0.5	6.0	ns
			3.3 V ± 0.3V	0.5	2.3	4.0	0.5	5.5	
			5.0V ± 0.5V	0.5	1.7	3.0	0.5	4.0	

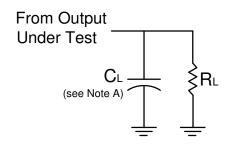
# **Operating Characteristics**

 $T_A = +25$ °C

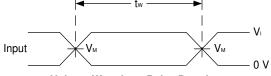
Parameter		Test Conditions	V <sub>CC</sub> = 1.8V	V <sub>CC</sub> = 2.5V	V <sub>CC</sub> = 3.3V	V <sub>CC</sub> = 5V	Unit
		Ooriditions	Тур	Тур	Тур	Тур	
$C_{pd}$	Power Dissipation Capacitance	f = 10MHz	3	3	4	6	pF



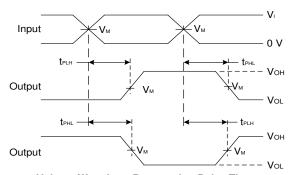
#### **Parameter Measurement Information**



V	Inp	outs				Б	<b>V</b> Δ
V <sub>CC</sub>	Vı	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	$R_L$	VΔ
1.8V±0.15V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	2 X V <sub>CC</sub>	30pF	1ΚΩ	0.15V
2.5V±0.2V	V <sub>CC</sub>	≤2ns	V <sub>CC</sub> /2	2 X V <sub>CC</sub>	30pF	500Ω	0.15V
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.5V	V <sub>CC</sub>	≤2.5ns	V <sub>CC</sub> /2	2 X V <sub>CC</sub>	50pF	500Ω	0.3V



**Voltage Waveform Pulse Duration** 



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

Figure 1 Load Circuit and Voltage Waveforms

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 10 MHz

C. The inputs are measured one at a time with one transition per measurement.

D. For the open drain device  $t_{PLZ}$  and  $t_{PZL}$  are the same as  $t_{PD}$ 

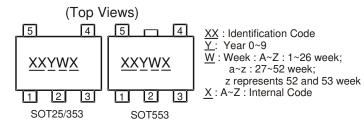
E. tpzL is measured at V<sub>M</sub>.

F. tpLz is measured at VoL +V $_{\!\Delta}$ 



### **Marking Information**

#### (1) SOT25, SOT353 and SOT553



Part Number	Package	Identification Code
74LVC1G06W5-7	SOT25	UM
74LVC1G06SE-7	SOT353	UM
74LVC1G06Z-7	SOT553	UM

#### (2) DFN Packages

(Top View)

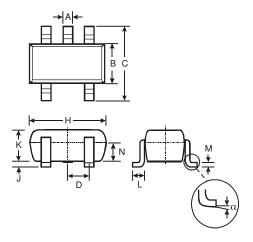
XX  $\underline{Y} \underline{W} \underline{X}$   $\underline{XX}$ : Identification Code  $\underline{Y}$ : Year 0~9

Y: Yeek: A~Z:1~26 week; a~z:27~52 week; z represents 52 and 53 week X:A~Z:Internal Code

Part Number	Package	Identification Code
74LVC1G06FS3-7	X2-DFN0808-4	WM
74LVC1G06FW5-7	X1-DFN1010-6 (Type B)	V5
74LVC1G06FW4-7	X2-DFN1010-6	UM
74LVC1G06FX4-7	X2-DFN1409-6	MD
74LVC1G06FZ4-7	X2-DFN1410-6	UM



Please see http://www.diodes.com/package-outlines.html for the latest version.

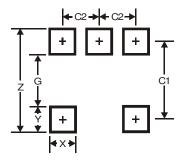


SOT25			
Dim	Min	Max	Тур
Α	0.35	0.50	0.38
В	1.50	1.70	1.60
С	2.70	3.00	2.80
D	-	-	0.95
Н	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
М	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	-
All Dimensions in mm			

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT25

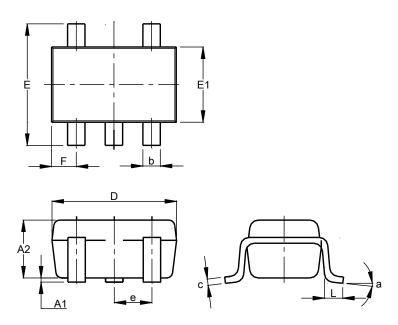


Dimensions	Value
Z	3.20
G	1.60
Х	0.55
Υ	0.80
C1	2.40
C2	0.95



Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **SOT353**

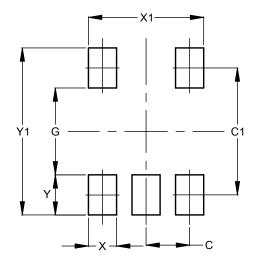


SOT353				
Dim	Min	Max	Тур	
<b>A</b> 1	0.00	0.10	0.05	
A2	0.90	1.00	1.00	
b	0.10	0.30	0.25	
С	0.10	0.22	0.11	
D	1.80	2.20	2.15	
Е	2.00	2.20	2.10	
E1	1.15	1.35	1.30	
е	e 0.650 BSC			
F	0.40	0.45	0.425	
L	0.25	0.40	0.30	
а	0°	8°		
All Dimensions in mm				

# **Suggested Pad Layout**

 $Please see \ http://www.diodes.com/package-outlines.html \ for the \ latest \ version.$ 

#### **SOT353**

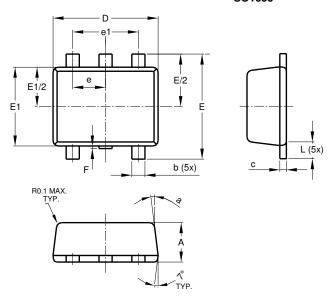


Dimensions	Value (in mm)
С	0.650
C1	1.900
G	1.300
Х	0.420
X1	1.720
Y	0.600
V1	2 500



Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **SOT553**

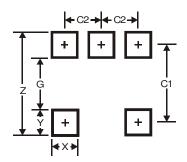


SOT553			
Dim	Min	Max	Тур
Α	0.55	0.62	0.60
b	0.15	0.30	0.20
С	0.10	0.18	0.15
D	1.50	1.70	1.60
Е	1.55	1.70	1.60
E1	1.10	1.25	1.20
е	0.50 BSC		
e1	1.00 BSC		
F	0.00	0.10	
L	0.10	0.30	0.20
а	6°	8°	7°
All Dimensions in mm			

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **SOT553**

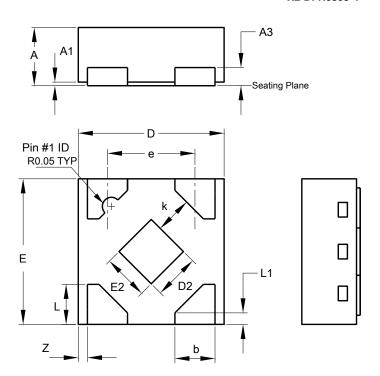


Dimensions	Value
Z	2.2
G	1.2
Х	0.375
Υ	0.5
C1	1.7
C2	0.5



Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN0808-4

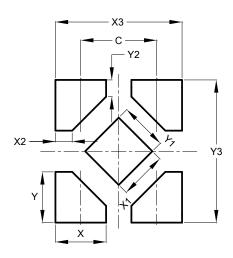


X2-DFN0808-4				
Dim	Min	Max	Тур	
Α	0.25	0.35	0.30	
<b>A</b> 1	0	0.04	0.02	
A3	-	-	0.13	
b	0.17	0.27	0.22	
D	0.75	0.85	0.80	
D2	0.15	0.35	0.25	
E	0.75	0.85	0.80	
E2	0.15	0.35	0.25	
е	1	-	0.48	
k	0.20	-	-	
L	0.17	0.27	0.22	
L1	0.02	0.12	0.07	
Z	-	-	0.05	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN0808-4

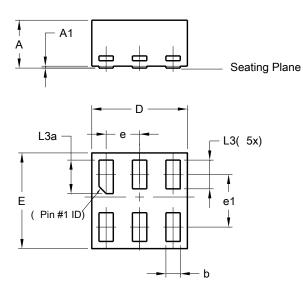


Dimensions	Value
С	0.480
Х	0.320
X1	0.300
X2	0.106
Х3	0.800
Υ	0.320
Y1	0.300
Y2	0.106
Y3	0.900



Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X1-DFN1010-6 (Type B)

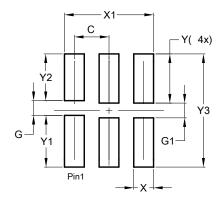


X1-DFN1010-6 (Type B)				
Dim	Min	Max	Тур	
Α	-	0.50	0.39	
A1	-	0.04	-	
b	0.12	0.20	0.15	
D	0.95	1.050	1.00	
Е	0.95	1.050	1.00	
е	0.35 BSC			
e1	0.55 BSC			
L3	0.27	0.30	0.30	
L3a		0.40	0.35	
All Dimensions in mm				

### **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### X1-DFN1010-6 (Type B)

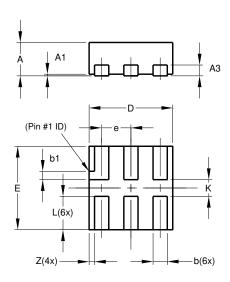


Dimensions	Value
Dilliensions	(in mm)
С	0.350
G	0.150
G1	0.150
Х	0.200
X1	0.900
Υ	0.500
Y1	0.525
Y2	0.475
Y3	1.150



Please see http://www.diodes.com/package-outlines.html for the latest version.

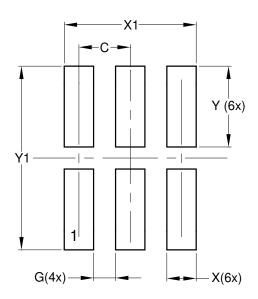
#### X2-DFN1010-6



X2-DFN1010-6			
Dim	Min	Max	Тур
Α		0.40	0.39
A1	0.00	0.05	0.02
А3			0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
Е	0.95	1.05	1.00
е			0.35
L	0.35	0.45	0.40
K	0.15		
Z			0.065
All Dimensions in mm			

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



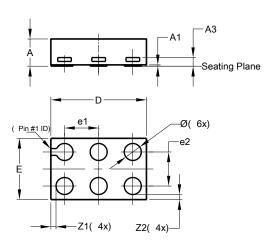
#### X2-DFN1010-6

Dimensions	Value (in mm)
С	0.350
G	0.150
Х	0.200
X1	0.900
Υ	0.550
Y1	1.250



Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1409-6 CHIP SCALE ALTERNATIVE

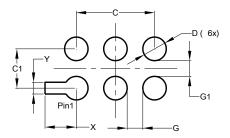


X2-DFN1409-6				
Dim	Min	Max	Тур	
Α	-	0.40	0.39	
A1	0	0.05	0.02	
A3	-	1	0.13	
Ø	0.20	0.30	0.25	
D	1.35	1.45	1.40	
Е	0.85	0.95	0.90	
e1	-	-	0.50	
e2	-	-	0.50	
<b>Z</b> 1	-	-	0.075	
<b>Z2</b>	-	1	0.075	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

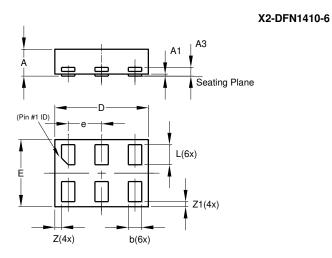
#### X2-DFN1409-6 CHIP SCALE ALTERNATIVE



Dimensions	Value	
Difficusions	(in mm)	
С	1.000	
C1	0.500	
D	0.300	
G	0.200	
G1	0.200	
X	0.400	
γ	0.150	



Please see http://www.diodes.com/package-outlines.html for the latest version.

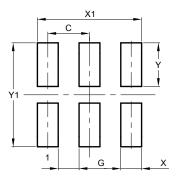


X2-DFN1410-6				
Dim	Min	Max	Тур	
Α		0.40	0.39	
A1	0.00	0.05	0.02	
A3		_	0.13	
b	0.15	0.25	0.20	
D	1.35	1.45	1.40	
E	0.95	1.05	1.00	
е		_	0.50	
L	0.25	0.35	0.30	
Z		_	0.10	
Z1	0.045	0.105	0.075	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### X2-DFN1410-6



Dimensions	,Value	
	(in mm)	
С	0.500	
G	0.250	
X	0.250	
X1	1.250	
Υ	0.525	
Y1	1.250	



#### **IMPORTANT NOTICE**

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel.

Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

#### LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

- A. Life support devices or systems are devices or systems which:
  - 1. are intended to implant into the body, or
  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

Copyright © 2016, Diodes Incorporated

www.diodes.com